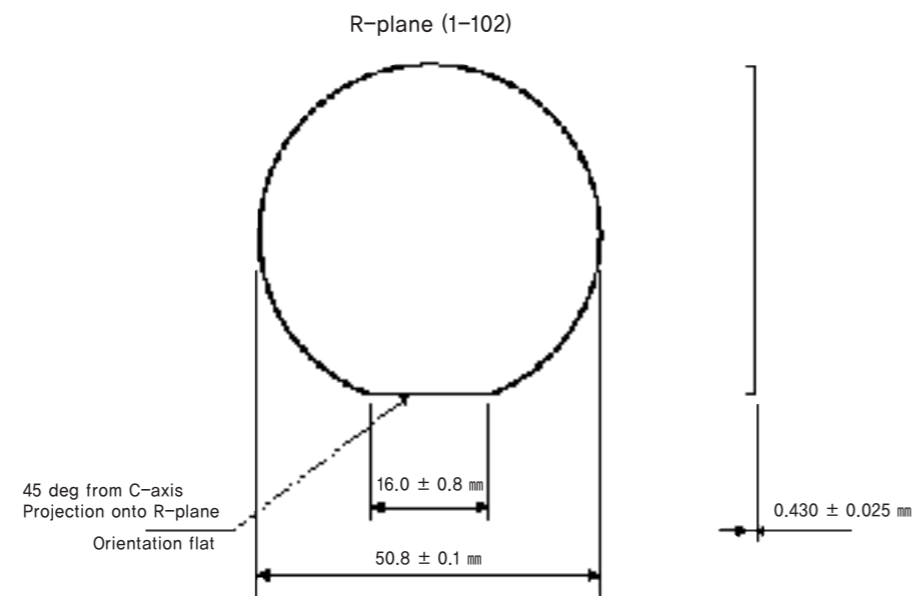
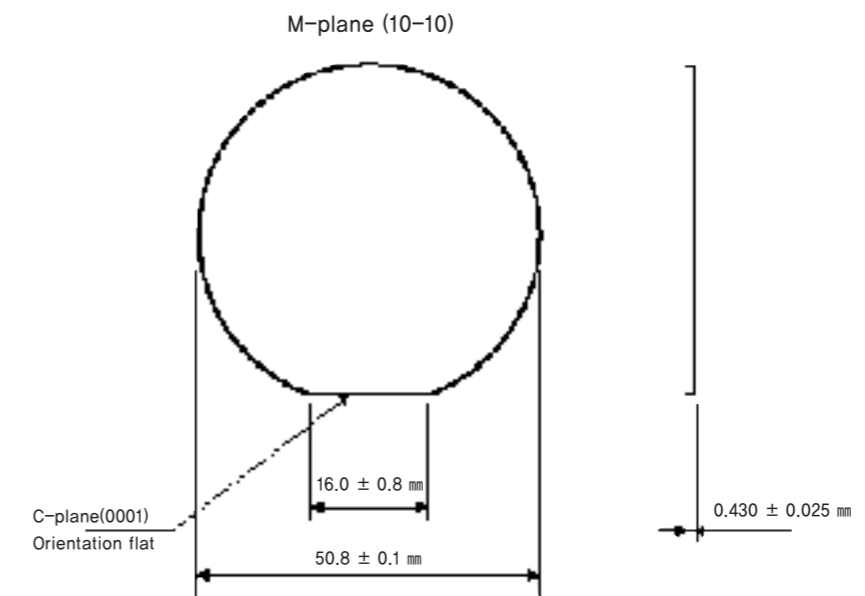


SAPPHIRE WAFER 2 inch R-plane



Property	Specification
Surface Orientation	R-plane (1-102)
Diameter	50.8 ± 0.1 mm
Thickness	0.430 ± 0.025 mm
Bow	≤ 10 μm
TTV	≤ 5 μm
Roughness (Ra)	≤ 0.3 nm
Orientation Flat	45° from C-axis Projection onto R-plane
Flat Length	16.0 ± 0.8 mm
Front Surface Finish	Epi-ready
Back Surface Finish	As-lapped (SSP) or Epi-ready (DSP)

SAPPHIRE WAFER 2 inch M-plane



Property	Specification
Surface Orientation	M-plane (10-10)
Diameter	50.8 ± 0.1 mm
Thickness	0.430 ± 0.025 mm
Bow	≤ 10 μm
TTV	≤ 5 μm
Roughness (Ra)	≤ 0.3 nm
Orientation Flat	C-plane (0001) ± 0.3°
Flat Length	16.0 ± 0.8 mm
Front Surface Finish	Epi-ready
Back Surface Finish	As-lapped (SSP) or Epi-ready (DSP)